



### **OPTICS 2019**

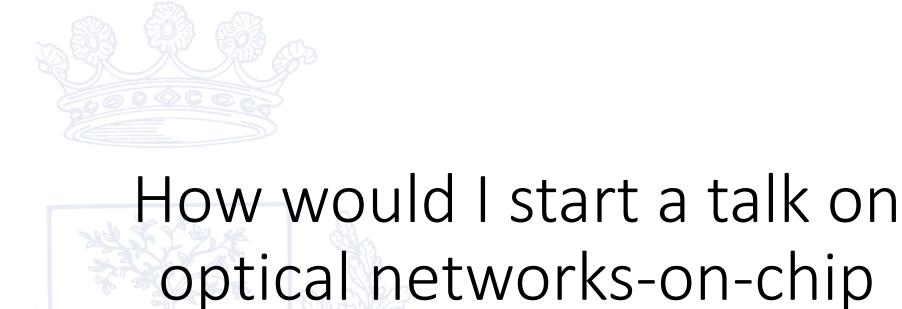
**Optical/Photonic Interconnects for Computing Systems** 

#### Panel:

## Bringing On-Chip Optical Interconnects into the Real World

Vladimir Stojanovic, *UC Berkeley* Yvain Thonnart, *CEA LETI* Bert Offrein, *IBM Zurich*  Laurent Vivien, *C2N*Ian O'Connor, *ECL* 

Moderator: Davide Bertozzi

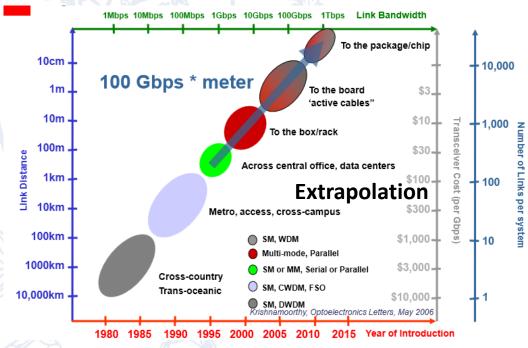


today?

### Moore's Law of Optical Links

# Photonics-to-electronics integration for optical interconnects in the early 21<sup>st</sup> century Ashok V.Krishnamoorthy\* Sun Microsystems SSG/Physical Sciences Center,9515 Towne Center Dr., San Diego, CA,92121, USA (Received 2 March 2006) We discuss the technical rationale, challenges, and potential for achieving "optics-to-the chip" via the intimate integration of photonics components such as lasers, detectors, and modulators with VLSI electronics. We review the progress made towards commercializing this technology for high-density optical transceivers and switching products. CLC number; TN256 Document code; A Article ID; 1673-1905(2006)03-0163-06

One order of magnitude deeper penetration into the communication hierarchy every 5 years.



History of penetration of optical data link into communication

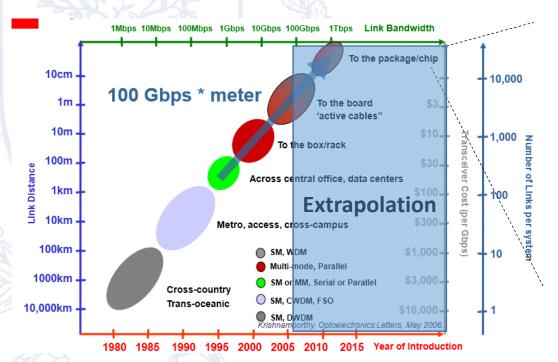
### Moore's Law of Optical Links

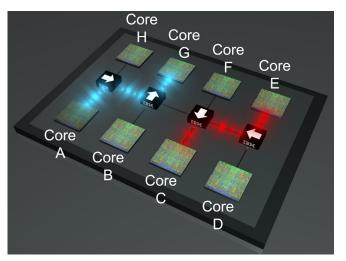
# Photonics-to-electronics integration for optical interconnects in the early 21st century Ashok V. Krishnamoorthy' Sun Microsystems SSG/Physical Sciences Center, 9515 Towne Center Dr., San Diego, CA, 92121, USA (Received 2 March 2006) We discuss the technical rationale, challenges, and potential for achieving "optics-to-the chip" via the intimate integration of photonics components such as lasers, detectors, and modulators with VLSI electronics. We review the progress made towards commercializing this technology for high-density optical

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transceivers and switching products.

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Source: IBM

If extrapolation were true,
Optical NoCs would be currently
mainstream!

### Moore's Law of Optical Links

Photonics-to-electronics integration for optical interconnects in the early 21<sup>st</sup> century

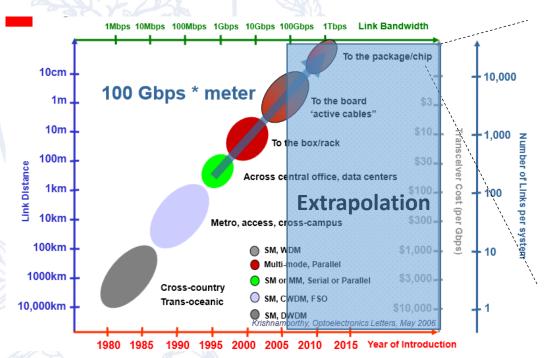
Ashok V. Krishnamoorthy\*
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But this is the reality (apart from papers)

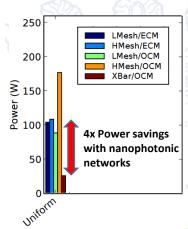




History of penetration of optical data link into communication

### Hype Cycle

Today



**Photonic Device Parameter** Value Optical fiber loss 0.5e-5 dB/cm Coupler loss  $0.5-1 \, dB$  $0.2 \, \mathrm{dB}$ Splitter loss Non-linearity loss at 30 mW 1 dB Modulator insertion loss 1 dB 2-4 dB/cm Waveguide loss Waveguide crossing loss  $0.05\,\mathrm{dB}$ 1e-4-1e-3 dB Filter through loss Filter drop loss 1 dB Photodetector loss 1 dB 30-50% Laser efficiency Receiver sensitivity -20 dBm

Peak of Inflated

Expectations

FPGA Accelerators
LPWA
STT-MRAM
Cryptocurrency Mining
SDR
3D XPoint
Solid-State DIMMs
Hybrid DIMMs
Silicon Photonics in Chip Interconnects
Sensor Fusion
Printed Electronics

liding Into the Trough

Hype Cycle for Semiconductors and Electronics Technologies, 2018 - Gartner

Golden age of architecture exploration (2007-2014)

Visibility

Plateau of Productivity

Slope of Enlightenment

Trough of Disillusionment What will happen here?

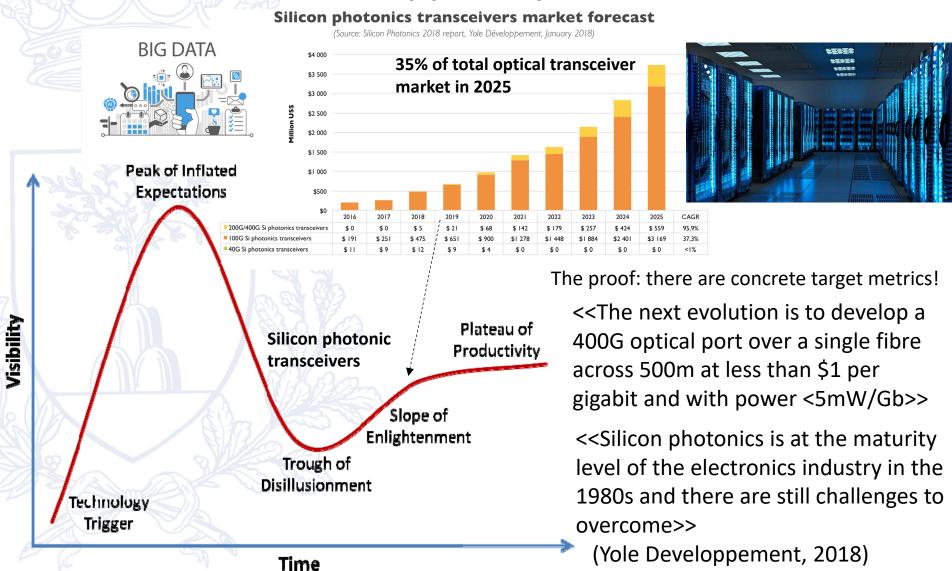
Time

At least there is a hope, and a task for the research community as well!

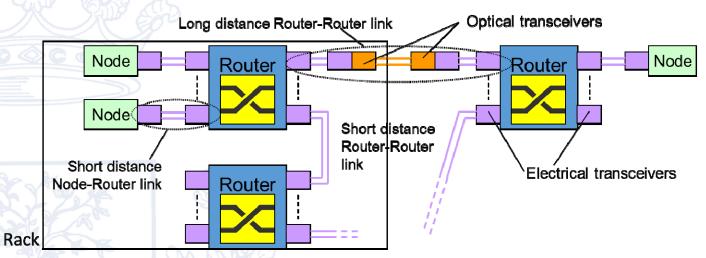


Silicon Photonic Transceivers have survived the trough of disillusionment, and are now in high demand on the market!

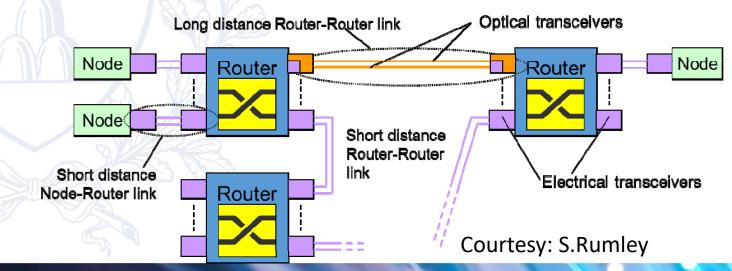
### Hype Cycle



### Where Silicon Photonic Links Are Now

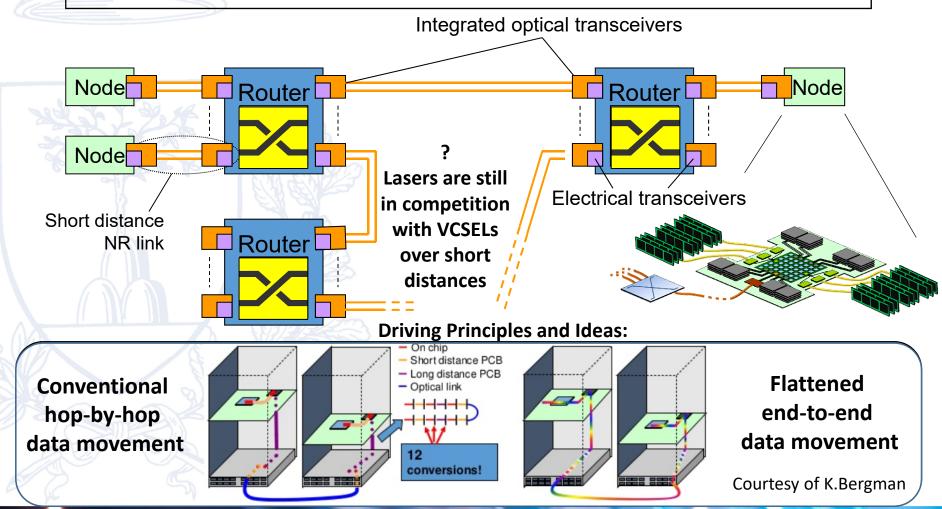


Silicon photonics uses co-integration techniques of optical components and/or transceivers with standard CMOS manufacturing process



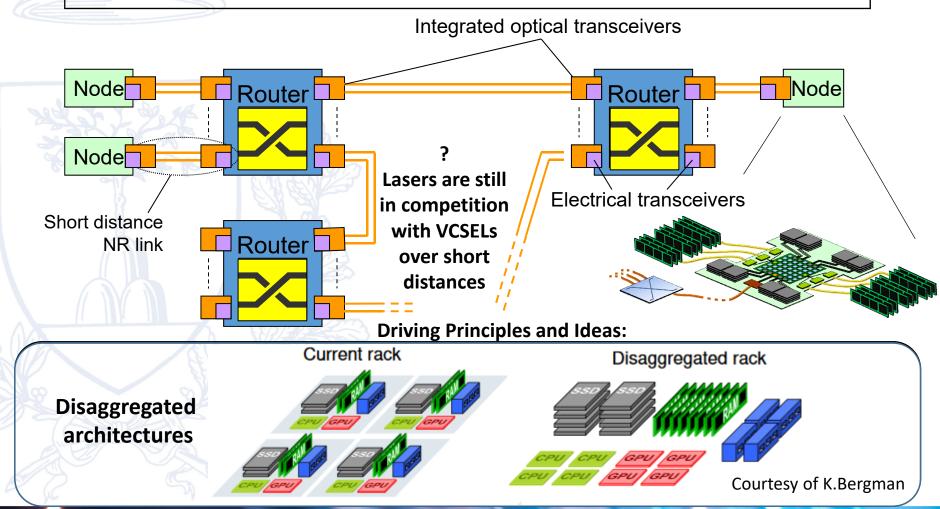
### Silicon Photonics: Game Changer?

Silicon photonics is delivering integrated optical transceivers and holds promise of bringing optical communications closer to and deeper into the processing node

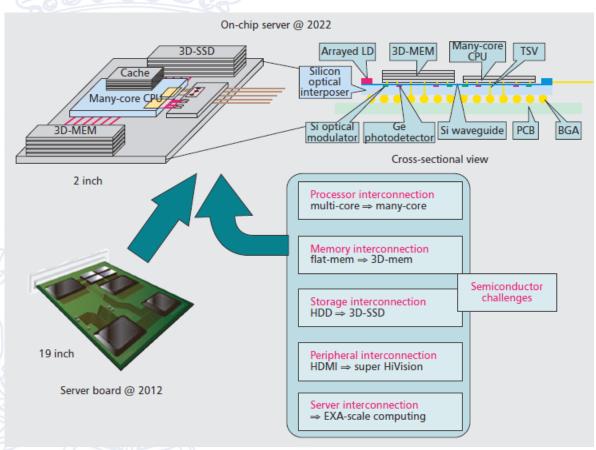


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## Looking Forward: Photonically-Integrated On-Chip Server



#### Key Advantages:

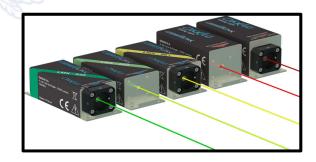
- 19 inches server boards shrink to 2 inches
- Huge Bandwidth: 6.6Tbps/cm<sup>2</sup>
- Si-Photonics Interposer's Size : 30 x 30 mm<sup>2</sup>
- Reduced Power

On Chip Server through Silicon Photonics Interposer Reference: "Silicon Photonics for next generation System integration Platform" Y.Arakawa et al., IEEE Communications Magazine, vol.51, Issue 3, pp.72-77, March 2013

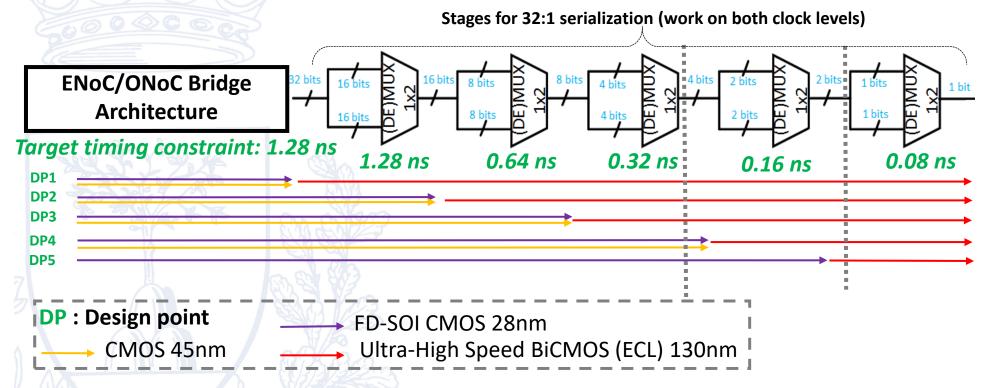
### Challenge

Silicon Photonics is not as low-power as it is advertised

It is a static-power dominated technology, and makes sense only if you are able to fully utilize it!

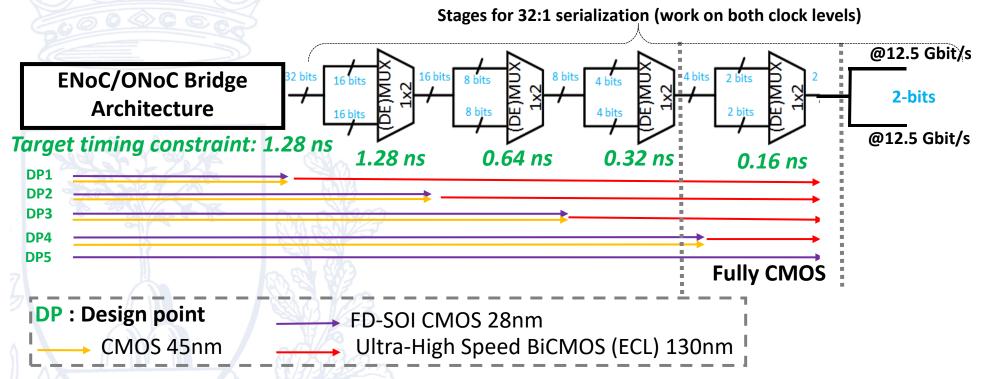


**Example Target Data Rate for source-destination connection: 25 Gbit/s** 



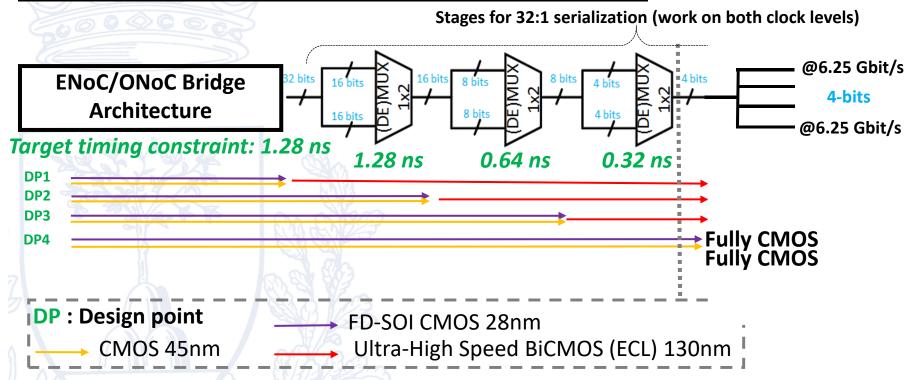
Higher signaling rates are paid with more power-consuming high-speed electronics at the interface

Target Data Rate for source-destination connection: @25 Gbit/s

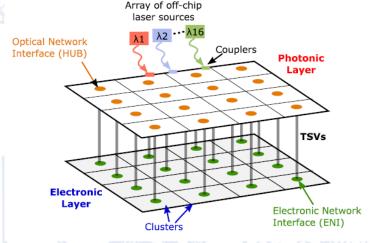


Only higher bit parallelism in optics can make fully-CMOS interface implementations feasible

Target Data Rate for source-destination connection: @25 Gbit/s



Further Increasing Optical Bit Parallelism makes more fully-CMOS design points feasible



So, why not using more parallelism in optics through WDM?

#### **Network-Level Trade-Offs Arise!**

	No. of TSVs		No. of Laser Sources		Total Network Power [W]		Worst-case SNR	
	25 Gbit/s	40 Gbit/s	25 Gbit/s	40 Gbit/s	25 Gbit/s	40 Gbit/s	25 Gbit/s	40 Gbit/s
1 bit	1216	2176	32	32	65.6	83.4	16.2	16.14
2 bits	1216	2176	48	48	7.4	79.7	13.13	13.1
4 bits	2176	2176	80	80	9.6	11.01	8.8	8.8

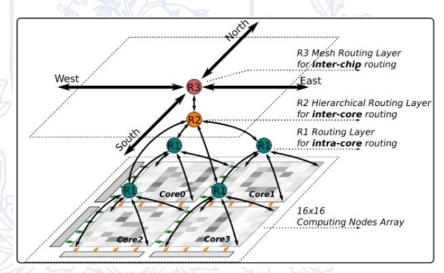
Optical parallelism comes with cost and signal integrity concerns, which are the price to pay for lower total power!

### Some Other Challenges

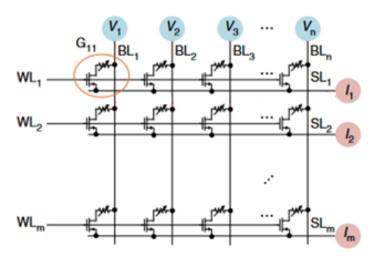
- Laser source integration
- Smaller size modulators are required
- Lower cost packaging and wafer-level testing
- Design and software
- Supply chain maturation similar to the semiconductor supply chain.
- New manufacturing solutions: zero-change approach on CMOS lines
- Temperature-aware design from the ground up

### **Not Only Communication!**

- The brain seems to have something very special about energy efficiency
- Brain-inspired computing may be the killer application for nonconventional and/or emerging technologies



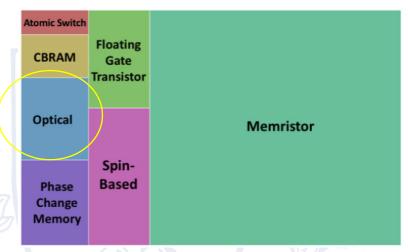
Asynchronous networks-on-chip



**Memristors** 

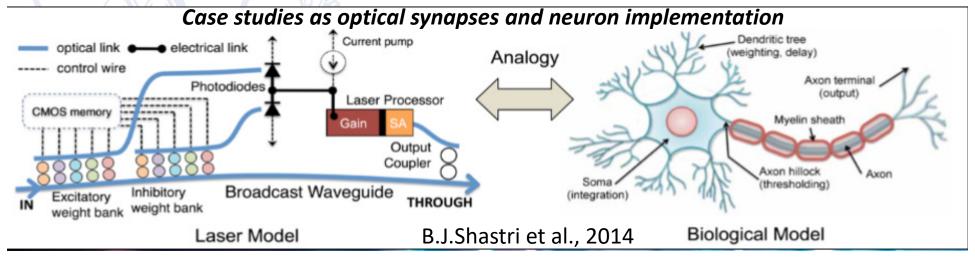
### The Role of Optics

 Non-standard device-level or circuit-level components for neuromorphic engineering



Promising technology for ultra-low fast operation, programmability and relatively low complexity.

C.D.Schuman et al., 2017 reports number of papers on neuromorphic computing making use of a specific technology (see box sizes)



### Questions for Discussion

- Optics deeper into the communication hierarchy?
  - ✓ Can optics replace multiple electronic conversions with 1 «major» conversion?
  - ✓ Can optics enable new system-level design paradigms?
- Optical networks-on-chip: a means of writing papers or a technology of practical relevance?
  - It may also depend on us!
- Optics as a «way to compute»: heading to the peak of inflated expectations? This would be a good sign....
- Electronics-photonics integration
  - ✓ monolithic integration vs. 2.5D vs. 3D integration?
  - ✓ Serdes-free interfaces? How to alleviate resynch. overhead?
- Design automation
  - ✓ Supporting technology or enabling it? Really beyond CMOS EDA, or reuse?
- We typically say that technology maturity has to improve
  - ✓ How far are we from such entry-level maturity level?
  - ✓ What about cost?



### THANK YOU

